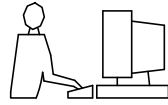
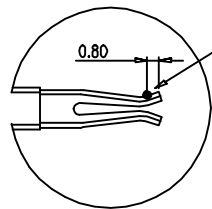
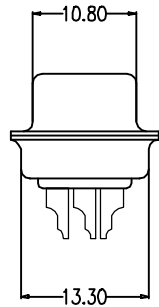
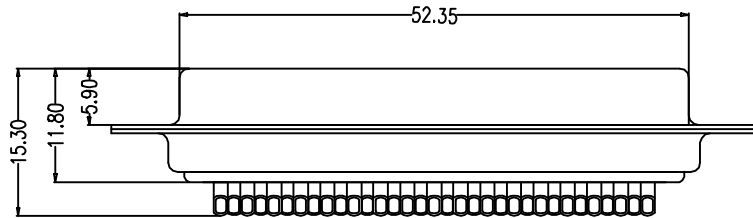
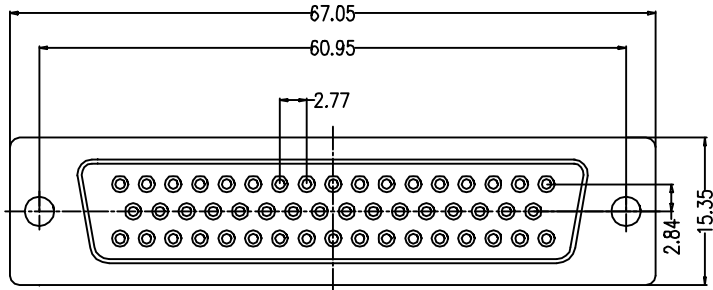


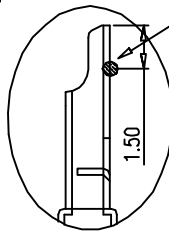
THIS IS A C.A.D. GENERATED DRAWING  
DO NOT MAKE MANUAL REVISIONS TO MASTER.



\* UNLESS OTHERWISE SPECIFIED TOLERANCES  
ON DECIMAL IS: ANGLE X.' ± 3' X.X' ± 1'  
UNIT: MM X. ± 0.30  
X.X ± 0.25  
X.XX ± 0.20  
X.XXX ± 0.15



GOLD PLATING  
TEST POINT



Tin PLATING  
TEST POINT

REMARK:

1.CHARACTERISTICS:

- 1.1. RATED VOLTAGE: 250V
- 1.2. RATED CURRENT: 3 AMP
- 1.3. CONTACT RESISTANCE: 25mohms MAX. INITIAL;40mohms MAX.AFTER
- 1.4. INSULATION RESISTANCE: 5000Mohms MIN.at 500V DC
- 1.5. DIELECTRIC STRENGTH: 1000VRMS
- 1.6. OPERATING TEMPERATURE RANGE: -55°C~85°C
- 1.7. INSERTION/EXTRACTION FORCE PER CONTACT: 1200g Max./20g Min

2.MATERIAL:

- 2.1. INSULATORS: PBT+30% G.F(UL94V-0) BLACK
- 2.2. CONTACTS: BRASS,1u" GOLD PLATING ON CONTACT AREA, 80~100u"Min BRIGHT TIN TOP OVER SOLDER AREA, 50u"Min NICKEL UNDER PLATE
- 2.3. FRONT SHELL: SPCC,80u" Min NICKEL TOP OVER,50u" Min COPPER UNDER PLATE
- 2.4. BACK SHELL: SPCC,80u" Min BRIGHT TIN TOP OVER, 50u" Min COPPER UNDER PLATE

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DRAWN Johnny Chen	DATE 02-08-22
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APPROVED Victor Lin	DATE 02-08-22
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SCALE	SHEET OF 1 OF 1	REV: 2.0
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DRAWING No MHDB50-SS
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THIS SERIES FULLY CONFORMS TO THE EUROPEAN UNION DIRECTIVES 2002/95/EC AND 2002/96/EC FOR RoHS COMPLIANCY.



**MH CONNECTORS ,  
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